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Applicant: Cheng-Yi Liu et al.

Title: Thinned Die Integrated Circuit Package

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Commissioner for Patents

Washington, D.C. 20231

We are transmitting herewith the attached:

☒ Revocation and Power of Attorney (2 pages)

☒ A return postcard.

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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on this 3 day of September, 2002.

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